

AMENDMENT TO THE CLAIMS:

1. (Currently Amended) A printed circuit board mounted with a wireless communication board, comprising:

multilayer structural conductive layers including a first conductive plane connected to power supply potential and a second conductive plane connected to ground potential;

~~wherein,~~wherein:

said first and second conductive planes are formed such that:~~one conductive plane interposes between the other conductive plane and a surface of said printed circuit board on a side where said wireless communication board is mounted, and an electric field generated by a potential difference between said power supply potential and said ground potential~~ the first conductive plane and the second conductive plane is concentrated on [[a]] one side of one of the first conductive plane and the second conductive plane, and

the conductive plane associated with the concentrated electric field and the wireless communication board are on different sides relative to the other one of the first conductive plane and the second conductive plane that is not associated with the concentrated electric field~~said the other conductive plane rather than a side of said one conductive plane.~~

2. (Currently Amended) The printed circuit board according to Claim 1, wherein:

said printed circuit board comprises a conductive belt that is formed in a conductive layer in which~~said the other conductive plane lies~~ the conductive plane associated with the concentrated electric field is disposed, and ~~located adjacent to said the other conductive plane associated with the concentrated field~~ with slits interposing between said conductive belt and ~~said the other conductive plane~~ with associated concentrated electric field; and

said conductive belt is electrically connected to ~~said one~~ the conductive plane not associated with the concentrated electric field.

3. (Currently Amended) The printed circuit board according to Claim 1, wherein:
said printed circuit board further comprises a U-shaped conductive member that encloses
a part of said printed circuit board to cover the surface of said printed circuit board in an area
over which said wireless communication board is mounted, and
said conductive member is electrically connected to ~~said one~~ the conductive layer not
associated with the concentrated electric field.

4. (Currently Amended) The printed circuit board according to Claim 1, ~~wherein:~~
~~said wherein~~ the other conductive plane associated with the concentrated electric field ~~has is~~
~~formed in~~ a smaller size than said ~~[[one]]~~ conductive plane not associated with the concentrated
electric field, and located within an area of ~~said one~~ the conductive plane not associated with the
concentrated electric field.

5. (Currently Amended) The printed circuit board according to Claim 1,
~~wherein:~~ wherein said printed circuit board comprises:
a conductive belt that is formed in a conductive layer in which ~~said the other~~ conductive
plane associated with the concentrated electric field lies, and located adjacently to ~~said the other~~
conductive plane associated with the concentrated electric field with slits interposing between
said conductive belt and ~~said the other~~ conductive plane associated with the concentrated electric
field; ~~[[and]]~~

a third conductive plane formed in a conductive layer that is located on an opposite side
to ~~said one~~ the conductive plane not associated with the concentrated electric field with respect
to ~~said the other~~ the conductive plane associated with the concentrated electric field; and

~~wherein:~~

said conductive belt and said third conductive plane are electrically connected to ~~said one~~
the conductive plane not associated with the concentrated electric field.

6. (Original) A wireless communication apparatus comprising:

a printed circuit board according to Claim 1; and

a chassis that houses said printed circuit board.

7. (Original) The wireless communication apparatus according to Claim 6, further
comprising:

a radio wave absorption member that is located inside said chassis, and absorbs an
electric field generated by a potential difference between said power supply potential and said
ground potential.